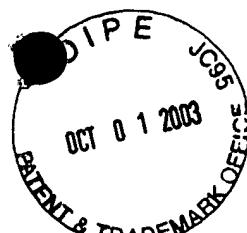


Docket No.: 50090-466



#10/B
10/15/03
PATENT Mailed

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Customer Number: 20277
Hiroshi HORIBE : Confirmation Number: 7602
Application No.: 10/050,166 : Group Art Unit: 2811
Filed: January 18, 2002 : Examiner: N. Parekh
For: SEMICONDUCTOR DEVICE AND WIRE BONDING APPARATUS

AMENDMENT

Mail Stop Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The following Amendment and Remarks are submitted in response to the Office Action dated April 17, 2003. Please amend the above-identified application as follows.

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